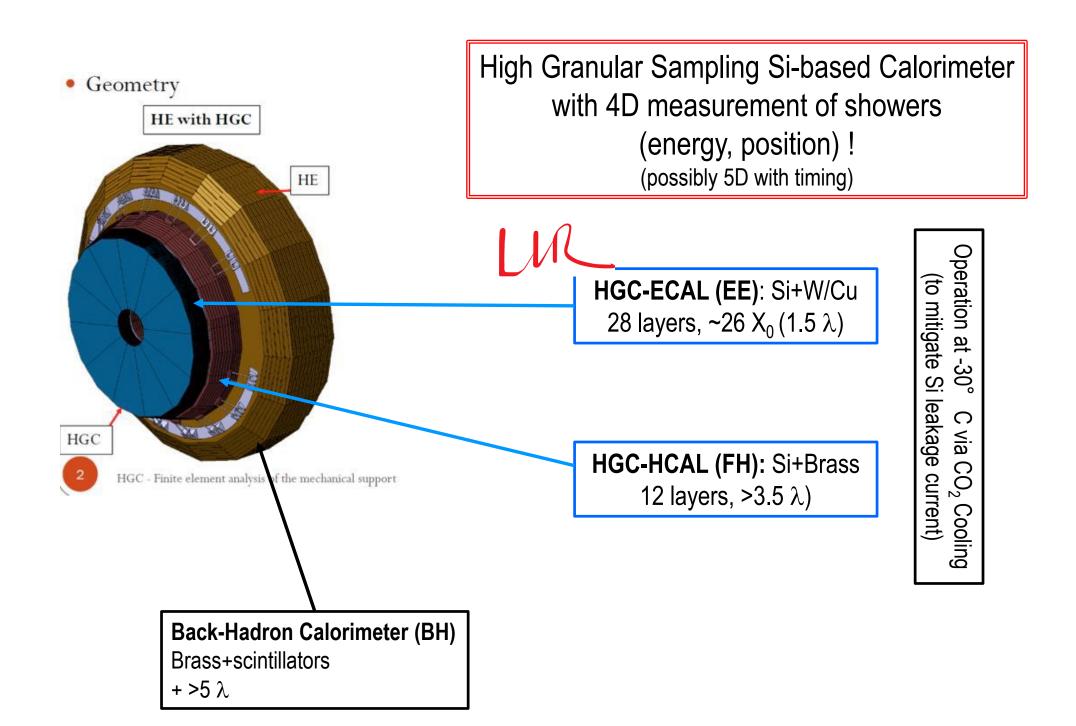


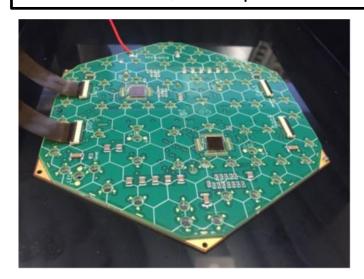
The HGCAL Project in a nutshell (1)



The HGCAL Project in a nutshell (2)

Modules

with 6 or 8" Hexagonal Si sensors, PCB, FE chip

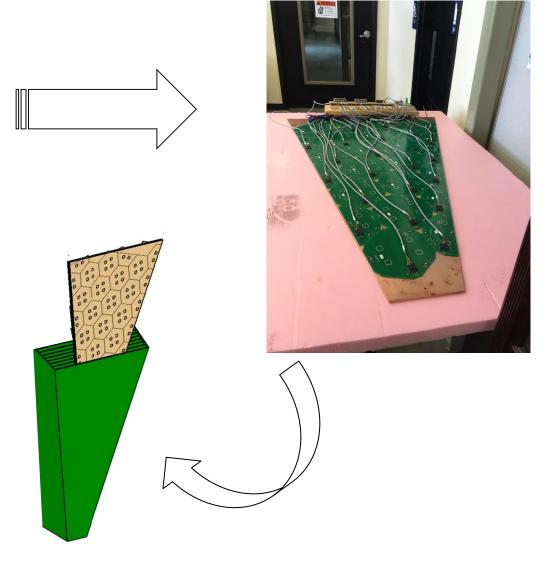


double sided (2 layers) Cassettes inserted in **mechanical structure** (containing absorber)

Modules mounted on both sides of

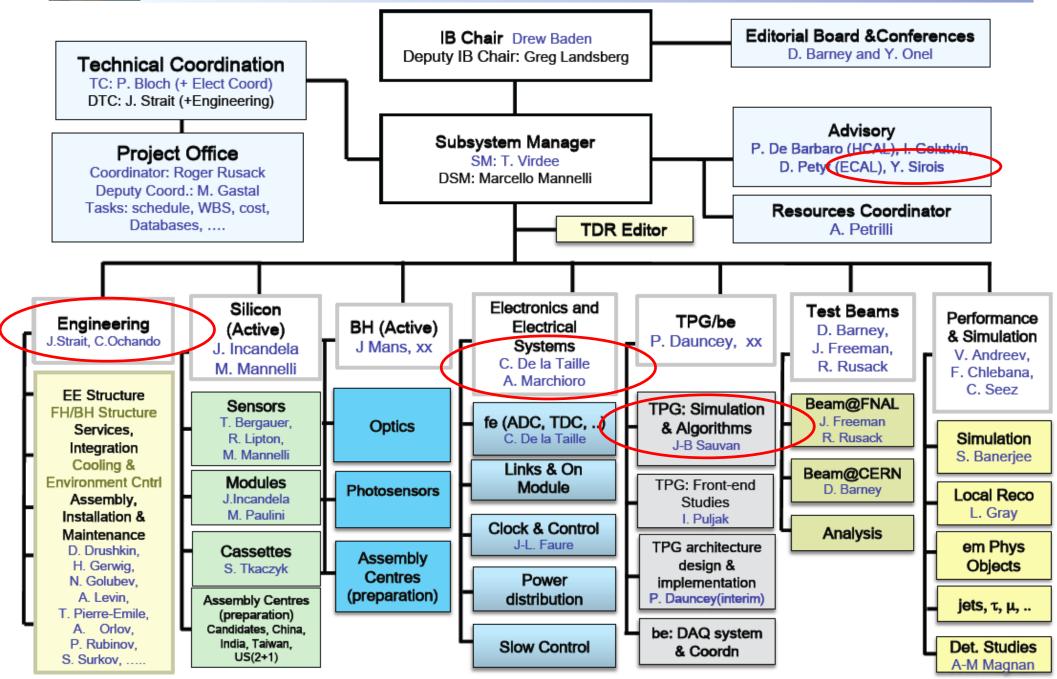
Cu Cooling plate with embedded pipes

== Cassettes





HGC Project Structure to Q1-17 (making Technical Choices, ..)



Timeline / Milestones

- > 27-28 June 2016: First CMS Comprehensive Review,
 - including external reviewers: L.Serin (ATLAS), Frank Simon (CALICE)
- **➤** End of 2017: Technical Design Report
 - including key technical choices:

Examples of Milestones for 2016

Subject	Item	Process/Criteria	Internal Milestone	LHCC Milestone
FH & BH Absorber	Brass or SS	Activation and Cost	Jun-16	Q2 2016
EE Mechanical Design	Full disk or phi sectors	Simulation / Performance& Design pros & cons	Oct-16	Q4 2016
FE electronics	Confirm 130 or 65 nm	Irradiation & Test vehicles	Oct-16	Q4 2016
DC-DC converters	Location: local or remote	Irradiation & Prototyping / System implications	Dec-16	Q4 2016
Electrical/optical links	Location: local or remote	Irradiation / System implications	Dec-16	
BH Active Material	Scintillator Type, Megatile Structure	Radiation hardness, ability to operate cold	Dec-16	Q4 2016
Cold Volume	Si only or full HGCAL	Integration studies / Performance & System Implications	Dec-16	Q4 2016
Si Sensors	p-in-n or n-in-p	Irradiation / Performance & System	Mar-17	Q1 2017
Si Sensors	6"or 8"	Dialogue with vendors	Mar-17	

Engineering
Silicon (Active)
BH (Active)
Electronics & Elect. Systems

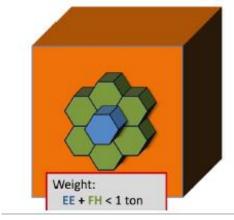
> End of 2019: Construction starts...

R&D is NOW!

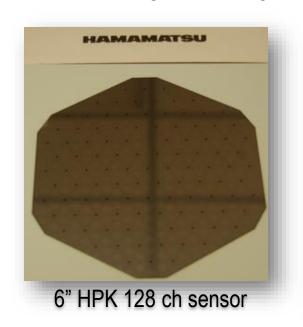
Recent Highlights: Test beams (1)

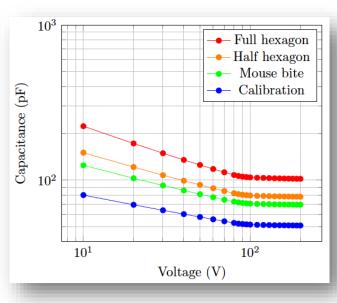
> Test beams:

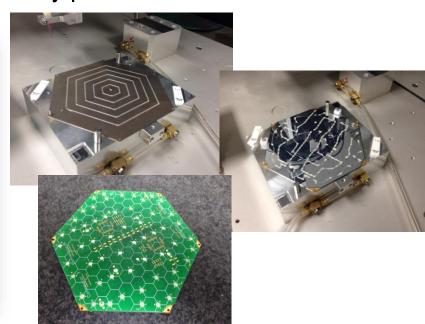
- 7 periods in 2016 (FNAL & CERN)
- Study: energy response, resolution, time,... simulation + very fast timing
 - with setups from 1 layer (April)
 to full HGC (28 EE layers + 12 FH layers, November)



- > Test beams at FNAL (April, May):
 - Very fast progress
 - Driving the design and test of Si sensors, PCB, assembly procedure of modules ...





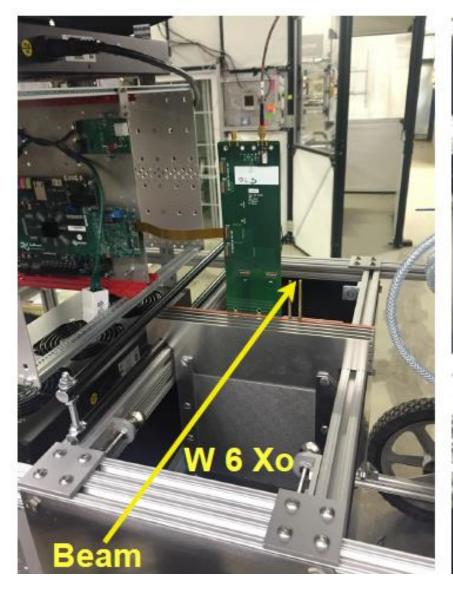


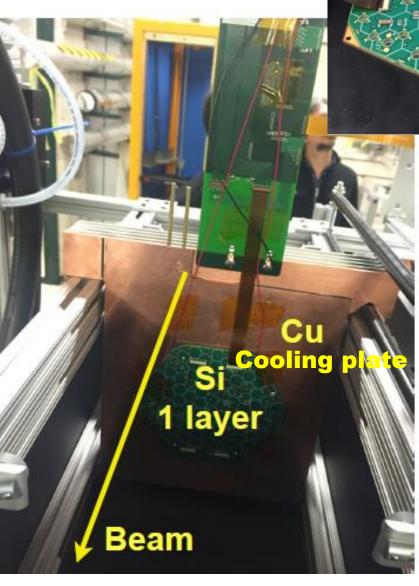
Recent Highlights: Test beams (2)

> FNAL Setup for April tests:

proton beam

■ 1 module, 6 X₀ before (W, Cu, W/Cu)



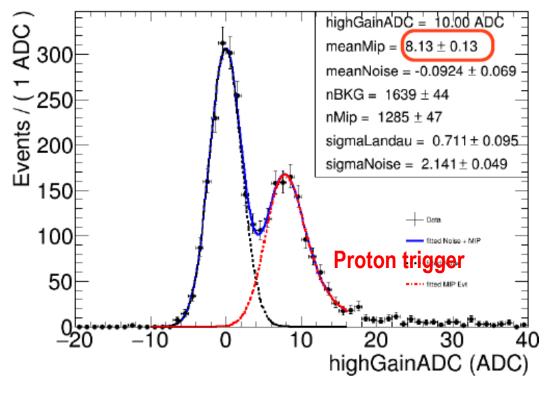


SKIROC2

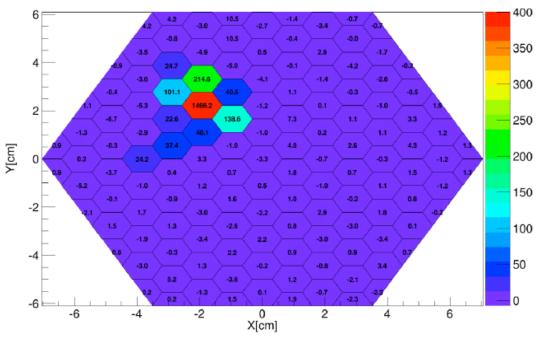
Recent Highlights: Test beams (3)

> First results:

120 GeV protons as a proxy for MIP and calibration



32 GeV electron after 6 X0



Size of cluster ~ 2 cm Pedestals subtracted

Next steps:

- <= 28 layers for tests in May [SKIROC2]</p>
- First tests at CERN in August/May (preceded by CALICE tests), then in November [SKIROC2 or SKIROC2_CMS if validated].

Recent Highlights: Front End

Ch. De La Taille et al., (Omega) Test FE pour TPG: Y. Geerebaert

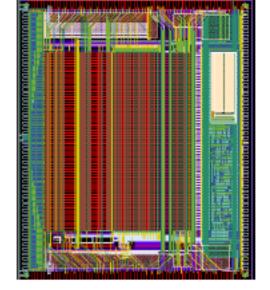
Stringent requirements for Front-End Electronics

- Low power (few mW), low noise (<2000 e-)
- High radiation (200 Mrad, 10^E16 N)
- System on chip (digitization, processing...)
- High speed readout (5-10 Gb/s)
- Timing information to 50ps accuracy

- SKIROC2_CMS expected in June.
- 4-5 boards will be equipped for tests (can start with SKIROC2)

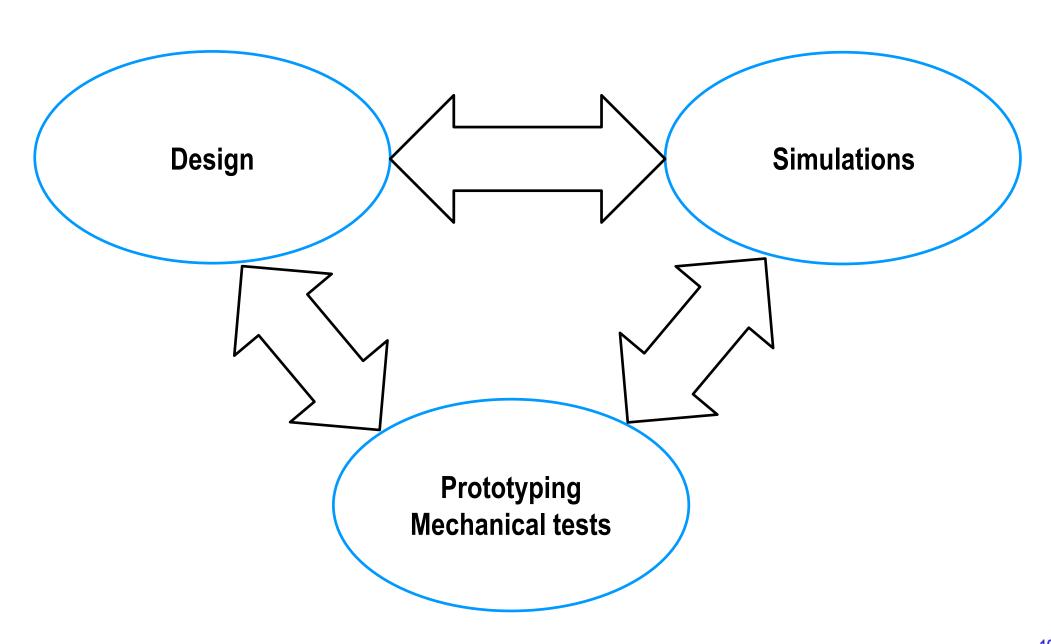
Milestones

```
⇒ end january
            Submit v0 fe chip (SKIROC-CMS)
15-Feb-16
                                                                      ⇒ end april
            Submit f.e. test vehicles in TSMC130 nm technology
31-Mar-16
            1st Comprehensive Review
                                               \Rightarrow 26-27 june
1-Jun-16
            1st results from f.e test vehicles
                                                  ⇒ 2<sup>nd</sup> test vehicles : full one channel
30-Sep-16
            Confirm choice of front-end electronics (130 nm) ?? Under study
31-Oct-16
            Define architecture & specs for LV/HV supply, links and on-module components
15-Dec-16
            Define location of DC-DC converters
15-Dec-16
            Define location of electrical/optical links
15-Dec-16
              ? Testbeam results of TOT architecture
            Submit V1 ASIC
                                  ⇒ First 32/64 ch ASIC with full functionnality
31-Mar-17
            Choice of Si sensors type: all n-on-p or mixed (i.e. n-on-p and p-on-n)
31-Mar-17
            2nd Comprehensive Review
1-Jun-17
            1st results from tests of V1 ASIC
30-Sep-17
            Submit TDR
1-Nov-17
            Submit V2 ASIC
30-Jun-18
```

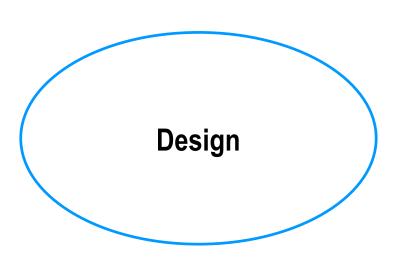


HGCAL at LLR: Mechanics (1)

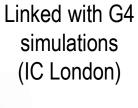
Focus on EE mechanics: W/C-fiber alveolar structure:

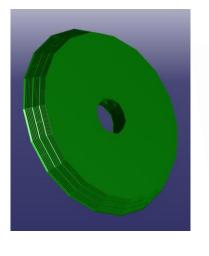


Focus on EE mechanics: W/C-fiber alveolar structure:

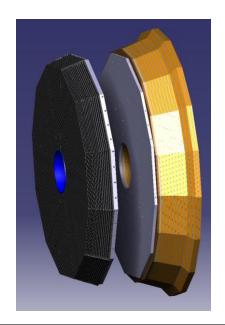






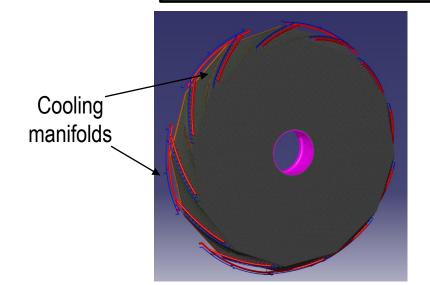






Study of EE/FH interface

Study of Services arrangement, Assembly, Integration (with CERN)





Cassettes insertion

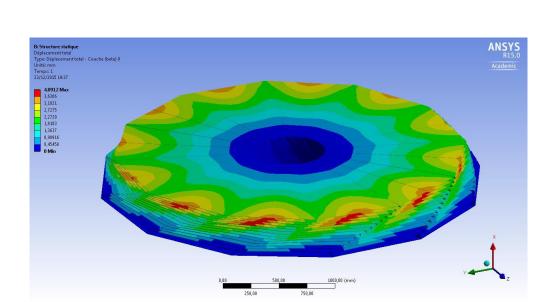
HGCAL at LLR: Mechanics (3)

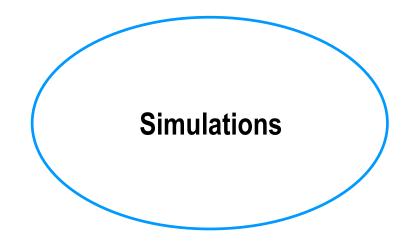
Focus on EE mechanics: W/C-fiber alveolar structure:

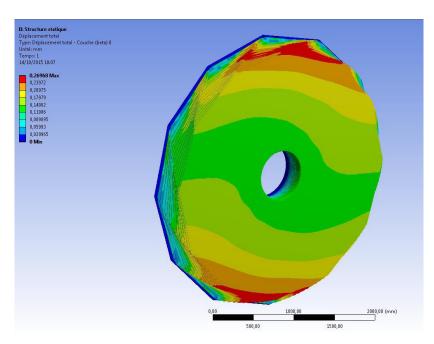
Assess Mechanical behavior via FEA simulations:

- in various positions,
- for various material properties,
- stresses from T° cycling

- ..







Focus on EE mechanics: W/C-fiber alveolar structure:

Mechanical tests on small samples Before/After irradiation, T° cycling,...



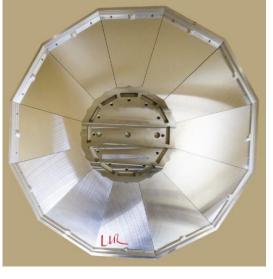
Note: Autoclave not big enough for real size production....



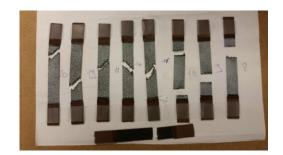




2 C-fiber "petal shape" alveoli



Mold for small disk of alveoli



Prototyping / Mechanical tests

- > LLR among the main drivers of the HGCAL L1 Trigger project
 - Now in strong collaboration with Split & CERN

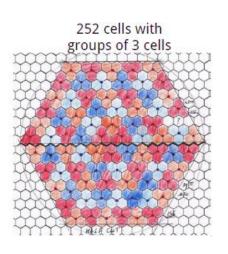
Architecture

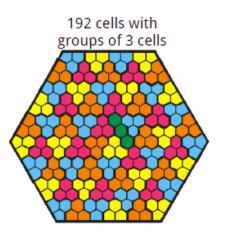
Front-End Studies

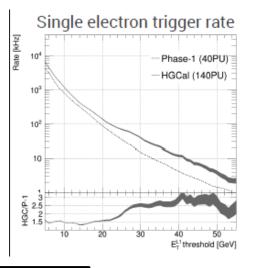
Simulation & Algorithms

Define baseline architecture for TP

- Work on trigger "raw data" (Data reduction, trigger cell geometry, ...)
- Development of emulator,+ standalone tools(digitization, ..)



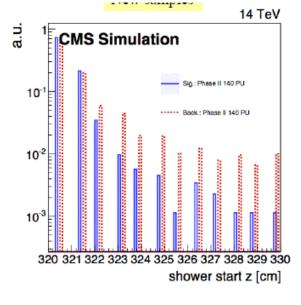


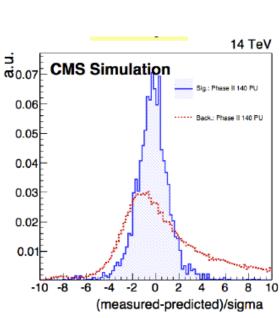


Besoin urgent d'un Test Bench SKIROC-CMS au LLR pour rester dans le jeu côté interface trigger avec le chip de FE

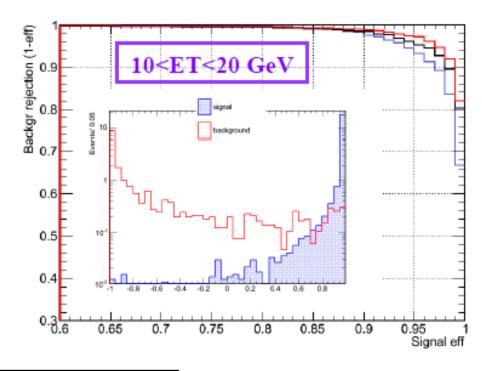
➤ Electrons/Photons (+Taus): Historical expertise of CMS-LLR.

- Develop reconstruction & identification of e/g objects for the TP.
- H \rightarrow ZZ, $\gamma\gamma$ main benchmarks.
- Will continue towards the TDR.
- Want to exploit the extraordinary potential for physics of this device
 (3D shower reconstruction, layer-by-layer PU subtraction, possibly adding timing, ...)





BDT electron identification



Also, wants to play an important role in CERN test beams (shifts, analysis/reconstruction/simulation)

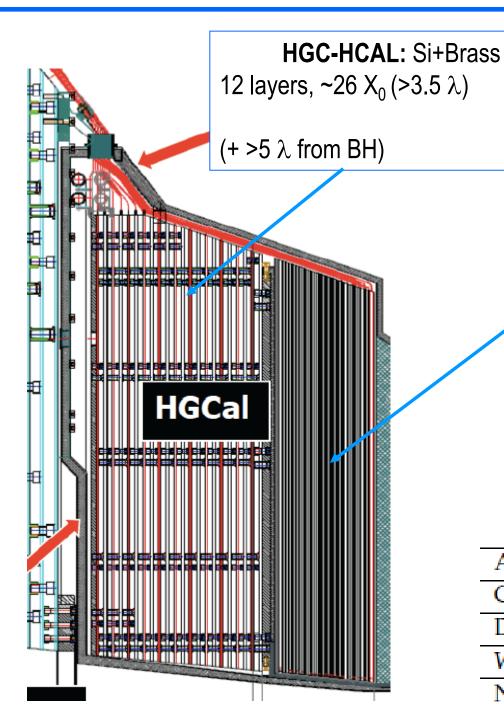
P2IO HGCFC (X/IN2P3 financed) crucial Post-doc here!

Conclusion

- LLR: Leading role during the Technical Proposal phase:
 - mechanics, L1 trigger, performances
 - Project is now in R&D Phase
 - must remain a key player for the Technical Design Report!
- > IN2P3 & LLR have a unique expertise in High Granular Calorimeters
 - we invented & validated the concept
 - we must be a driving force in this project!
- Current situation & prospects:
 - All studies, prototypes, ... were done within CMS common budget, previous material from CALICE, LLR internal budget...
 - Important P2IO support for mechanics +L1 (+IN2P3/X for post-doc) for R&D Phase (HGCFC Project)
 - ... but further support for IN2P3 is critical to have a decisive impact.

BACK UP SLIDES

HGCAL Parameters



Main interest of LLR

HGC-ECAL: Si+W/Cu 28 layers, ~26 X_0 (1.5 λ) 10 x 0.65 X_0 + 10 x 0.88 X_0 + 8 x 1.26 X_0

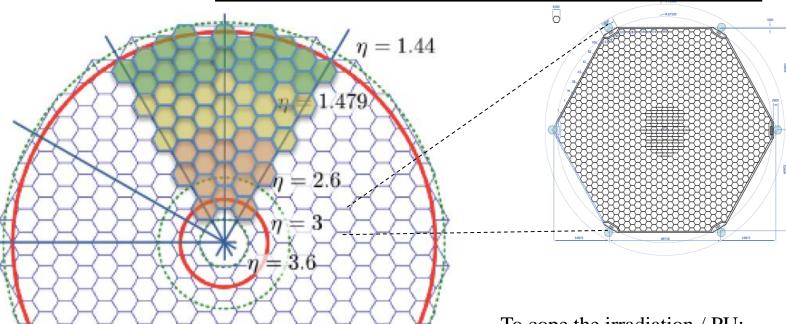
Operation at -30° C via CO₂ Cooling (to mitigate Si leakage current)

Table 3.2: Parameters of the EE and FH.

	EE	FH	Total
Area of silicon (m ²)	380	209	589
Channels	4.3M	1.8M	6.1M
Detector modules	13.9k	7.6k	21.5k
Weight (one endcap) (tonnes)	16.2	36.5	52.7
Number of Si planes	28	12	40

HGCAL Cells Geometry

Hexagonal 6" Si wafer (256 or 512 channels

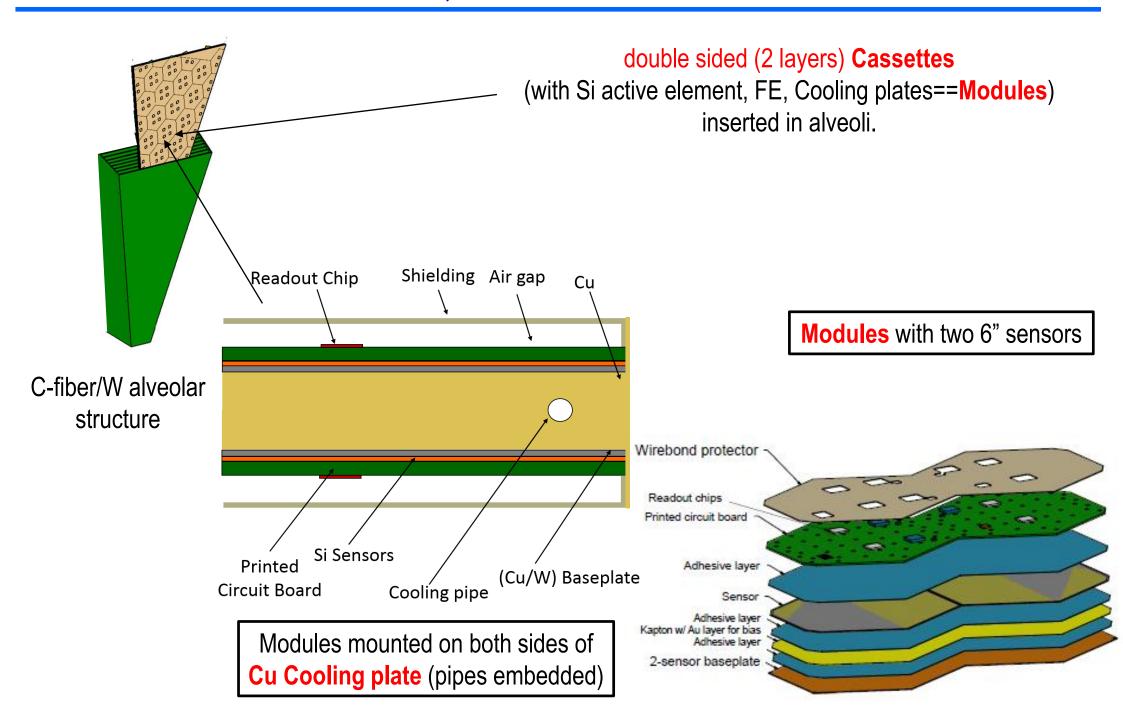


To cope the irradiation / PU:

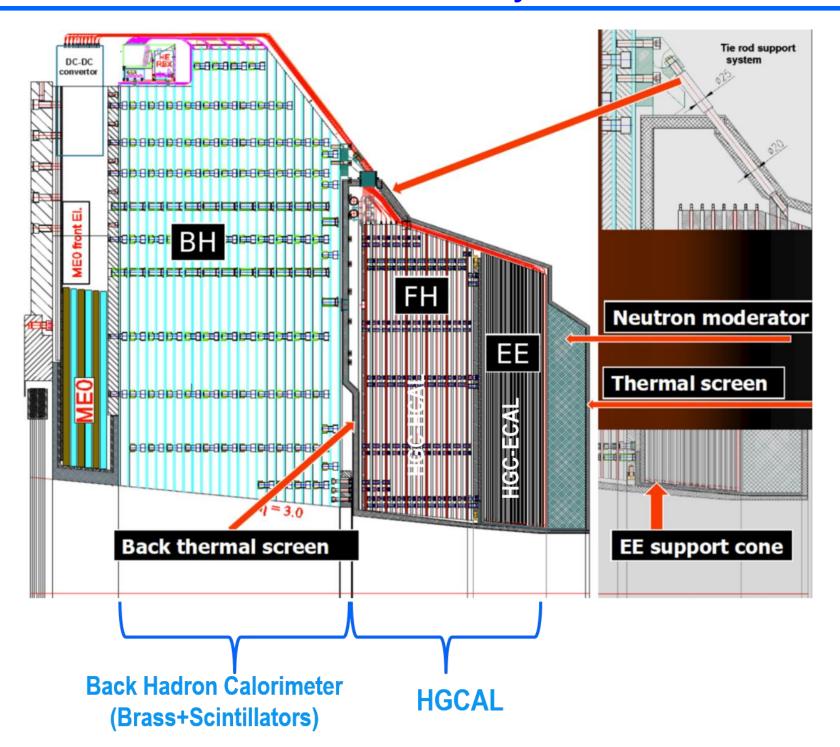
- η-dependent depletion of Si
- η-dependent cell size

Thickness	$300 \mu \mathrm{m}$	200 μm	$100\mu\mathrm{m}$	
Maximum dose (Mrad)	3	20	100	
Maximum n fluence (cm ⁻²)	6×10^{14}	2.5×10^{15}	1×10^{16}	
EE region	R > 120 cm	$120 > R > 75 \mathrm{cm}$	$R < 75 \mathrm{cm}$	
FH region	R > 100 cm	$100 > R > 60 \mathrm{cm}$	$R < 60 \mathrm{cm}$	
Si wafer area (m²)	290	203	96	
Cell size (cm ²)	1.05	1.05	0.53	
Cell capacitance (pF)	40	60	60	
Initial S/N for MIP	13.7	7.0	3.5	
S/N after 3000 fb ⁻¹	6.5	2.7	1.7	

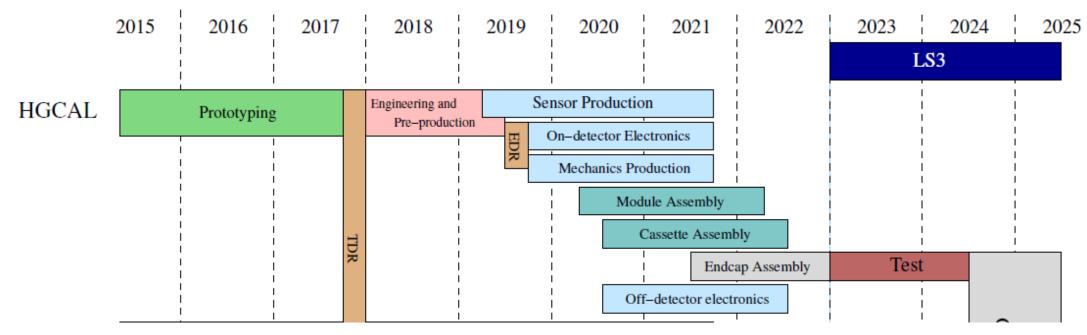
ECAL, Cassettes & Modules



HGCAL General Layout



Timeline



 Technical Proposal published in Summer 2015 (since then, many things have changed...)



- Technical Design Report for end of 2017 beginning of 2018.
- Installation during LS3

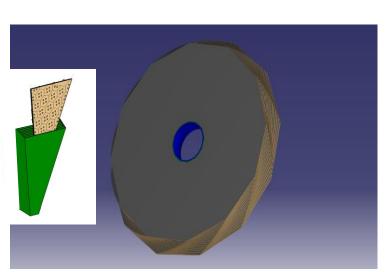
Test Beam Plans and Goals

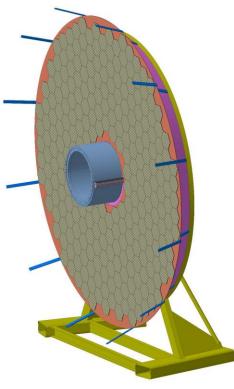
FNAL	Single module with ≤6 X ₀ absorber	March 25 – April 5	Complete Construction and first results are shown today
H2 (SPS)	Fast timing of irradiated diodes and a full hexagonal sensor	18-27 April	Now sharing a period in H2 for several fast-timing devices
FNAL	Full 28-layer EE (tbd)	May 18 - 31	
H2 (SPS)	Fast timing, as above	1-8 June	Extra period requested due to late arrival of SPS beam
T9 (PS)	Possibly a few full modules (tbd)	15-22 June	
H2 (SPS)	Full 28-layer EE (tbd)	31 Aug – 7 Sept	Moved as late as possible. Preceded by CALICE tests.
H2 (SPS)	28-layer EE + 12-layer FH (tbd)	9-14 Nov	Beam area will be available ~2 months before our tests. Cosmics?

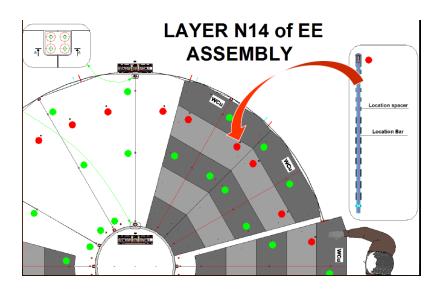
Goals: measure energy response, time and position resolutions, compare to simulation

EE mechanical structure options

3 different designs under study (with different level of maturity)







(A) W/C-fiber Alveolar Structure

- phi-sector Disks,
- WITH INSERTABLE_cassettes

(B) Full Disk

Inspired from PreShower experience

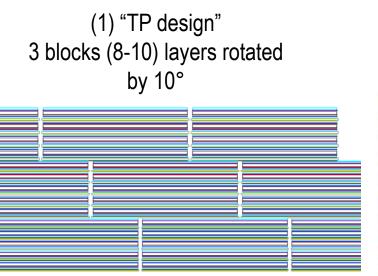
(C) "Tie-rods" design

- Variant of "full disk"
- Made from 30° cassettes,
 connected in inner/outer periphery
 +tie-rods + spacers

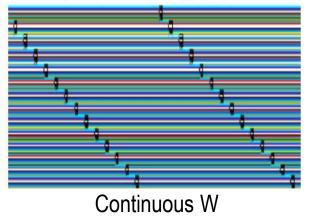
Physics (2)

> (A) Phi-sector Disks

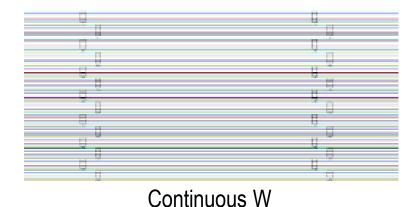
Various configurations simulated



(2) Disks rotated every 2° layer by layer (or every 2 layers==1 cassette)



(3) Disks with staggered layers (ever 2nd or 3rd)



Active-to-active gap: mainly created by C-fiber alveoli (+ Si guard ring, mechanical tolerance): 0.5 – <1cm

